

ABSTRACT

Provided is a conductive paste composition that contains an epoxy resin as a resin component and that is capable of realizing favorable thermal shock resistance and favorable moist heat resistance after curing. The conductive paste composition contains (A) a conductive powder, (B) an epoxy resin which serves as a resin component, (C) a curing agent, and (D) a curing accelerator. The (B) epoxy resin includes at least one type of epoxy resin having an epoxy equivalent of 500 g/eq or more. The (C) curing agent is a phenolic ester compound having a structure represented by formula (1). In the formula, R is a C1 to C10 alkyl group, a phenyl group, an aralkyl group, an alkoxyl group, or a halogen atom. In the formula, X is a hydrogen atom or an ester structure represented by -C(=O)-A (where A is a C1 to C6 alkyl group). In the formula, Z is a C1 to C15 divalent hydrocarbon group. In the formula, m is an integer from 0 to 4, and n is a number having an average value from 0 to 2.